Takeharu Kuroiwa

List of Publications by Year in descending order

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		933447	677142
30	516	10	22
papers	citations	h-index	g-index
30	30	30	358
30	30	30	330
all docs	docs citations	times ranked	citing authors

#	Article	IF	CITATIONS
1	Practical applications of SiC-MOSFETs and further developments. Semiconductor Science and Technology, 2016, 31, 034003.	2.0	30
2	Influence of Growth Pressure and Addition of HCl Gas on Growth Rate of 4H-SiC Epitaxy. Materials Science Forum, 2015, 821-823, 133-136.	0.3	4
3	Evaluation of distribution of exchange coupling in CoFe/Ru/CoFe synthetic antiferromagnetic structure after annealing. Journal of Applied Physics, 2009, 105, .	2.5	4
4	Suppression of Switching-Field Variation by Surface Oxidation Depending on the Shape of the CoFeB Free Layer. IEEE Transactions on Magnetics, 2007, 43, 2352-2354.	2.1	5
5	Magnetization Chirality of Ni-Fe and Ni-Fe/Mn-Ir Asymmetric Ring Dots for High-Density Memory Cells. Materials Science Forum, 2006, 512, 171-176.	0.3	2
6	Transition between onion states and vortex states in exchange-coupled Ni–Feâ^•Mn–Ir asymmetric ring dots. Journal of Applied Physics, 2006, 99, 08G303.	2.5	3
7	Leakage current characteristics of Ptâ^•Bi4â^'xLaxTi3O12â^•Ru ferroelectric capacitors fabricated on metal-organic chemical vapor deposited Ru films. Journal of Applied Physics, 2006, 100, 014108.	2.5	1
8	Thermal robustness in synthetic antiferromagnetic free layer for magnetic random access memory applications. Journal of Applied Physics, 2006, 99, 08C911.	2.5	3
9	Magnetically pinned ring dots for spin valve or magnetic tunnel junction memory cells. Journal of Magnetism and Magnetic Materials, 2005, 286, 31-36.	2.3	21
10	High-temperature operations of rotation angle sensors with spin-valve-type magnetic tunnel junctions. IEEE Transactions on Magnetics, 2005, 41, 3628-3630.	2.1	1
11	Fatigueless Ferroelectric Capacitors with Ruthenium Bottom and Top Electrodes Formed by Metalorganic Chemical Vapor Deposition. Japanese Journal of Applied Physics, 2005, 44, L378-L380.	1.5	4
12	Control of pinned layer magnetization direction in spin-valve-type magnetic tunnel junction with an IrMn layer. Journal of Applied Physics, 2004, 95, 6795-6797.	2.5	1
13	Read-Cycle Endurance of Magnetic Random Access Memory Elements. IEEE Transactions on Magnetics, 2004, 40, 2631-2633.	2.1	O
14	Magnetization chirality due to asymmetrical structure in Ni-Fe annular dots for high-density memory cells. Journal of Applied Physics, 2004, 95, 6714-6716.	2.5	35
15	Chemical Vapor Deposition of Ru Bottom Electrode for Ferroelectric Bi $4 - x$ La x Ti 3 O 12 Capacitors. Integrated Ferroelectrics, 2003, 59, 1437-1443.	0.7	O
16	Chemical Vapor Deposition of Ru Bottom Electrode for Ferroelectric Bi4 \hat{a}^{*} x La x Ti3O12 Capacitors. Integrated Ferroelectrics, 2003, 59, 1437-1443.	0.7	2
17	Preparation of Bi3.25+xLa0.75Ti3O12+yFilms on Ruthenium Electrodes. Japanese Journal of Applied Physics, 2002, 41, 2105-2109.	1.5	14
18	Improved fabrication process for Ru/BST/Ru capacitor by liquid source chemical vapor deposition. Thin Solid Films, 2002, 409, 8-14.	1.8	9

#	Article	IF	CITATIONS
19	Effects of Oxygen Vacancy Diffusion on Leakage Characteristics of Pt/(Ba0.5Sr0.5)TiO3/Pt Capacitor. Japanese Journal of Applied Physics, 2000, 39, L416-L419.	1.5	12
20	Model of leakage characteristics of (Ba, Sr)TiO3 thin films. Applied Physics Letters, 1998, 73, 954-956.	3.3	82
21	Influence of Buffer Layers and Barrier Metals on Properties of (Ba,Sr)TiO3Films Prepared by Liquid Source Chemical Vapor Deposition. Japanese Journal of Applied Physics, 1997, 36, 5874-5878.	1.5	10
22	Novel stacked capacitor technology for 1-Gbit DRAMs with (Ba,Sr)TiO3 thin films. Electronics and Communications in Japan, 1997, 80, 70-78.	0.2	2
23	Determination of Structure Factors of Al ₂ O ₃ by means of Large Angle Convergent Beam Electron Diffraction. Materials Transactions, JIM, 1995, 36, 1344-1348.	0.9	2
24	Dielectric Relaxation of (Ba,Sr) TiO3Thin Films. Japanese Journal of Applied Physics, 1995, 34, 5478-5482.	1.5	87
25	Dielectric Properties of(BaxSr1-x)TiO3Thin Films Prepared by RF Sputtering for Dynamic Random Access Memory Application. Japanese Journal of Applied Physics, 1994, 33, 5187-5191.	1.5	110
26	Electric Properties of SrTiO3Thin Films Prepared by RF Sputtering. Japanese Journal of Applied Physics, 1992, 31, 3025-3028.	1.5	52
27	Characteristics of a Schottky Barrier Diode and the SiC Wafers Sliced by Wire Electrical Discharge Machining. Materials Science Forum, 0, 778-780, 784-787.	0.3	0
28	Demonstration of High Quality 4H-SiC Epitaxy by Using the Two-Step Growth Method. Materials Science Forum, 0, 778-780, 167-170.	0.3	4
29	Demonstration of High Quality 4H-SiC Epitaxial Growth with Extremely Low Basal Plane Dislocation Density. Materials Science Forum, 0, 778-780, 91-94.	0.3	9
30	Properties of a SiC Schottky Barrier Diode Fabricated with a Thin Substrate. Materials Science Forum, 0, 778-780, 820-823.	0.3	7